



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS340U	HNZJ*Z25S81T	A	ZA41	2016-08-24
Amount	UoM	Unit type	ST ECOPACK Grade	
98.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.50X2.16X3.68	1	J bend	
Comment	Package: SMB CLIP (SOD 6 NEW)			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HNZJ*Z25581T									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.143	mg	supplier	die	Silicon (Si)	7440-21-3		1.086	mg	950131	11082				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	6124	71				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	875	10				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1750	20				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.005	mg	4374	51				
				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	4374	51				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	6124	71				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	875	10				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1750	20				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.007	mg	6124	71				
				supplier	polymer die coating	Durimide	proprietary		0.020	mg	17498	204				
				Leadframe & Clip	Copper and its alloy	40.721	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		40.701	mg	999509	415316
								Supplier	Alloy	Zinc (Zn)	7440-66-6		0.002	mg	49	20
Supplier	Alloy	Iron (Fe)	7439-89-6						0.004	mg	98	41				
Supplier	Alloy	Iron Phosphide(FeP)	26508-33-8						0.014	mg	344	143				
Die attach	Other organic material	2.314	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.058	mg	25065	592				
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.115	mg	49697	1173				
				JIG R	soft solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	2.141	mg	925238	21847				
Encapsulation	Other organic material	52.886	mg	Supplier	Molding Compound	silica fused	7631-86-9		39.134	mg	739969	399327				
				Supplier	Molding Compound	silica quartz	14808-60-7		10.578	mg	200015	107939				
				Supplier	Molding Compound	phenolic resin	9003-35-4		2.645	mg	50013	26990				
				Supplier	Molding Compound	carbon black	1333-86-4		0.529	mg	10003	5398				
Finishing	Other inorganic material	0.936	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		0.936	mg	1000000	9551				